

## In The Claims

Claims 1-230 (canceled)

- 5     231. (currently amended) A chip package comprising:  
        a first die having a top surface at a horizontal level;  
        a patterned wiring layer over said horizontal level, wherein said patterned wiring  
layer comprises a first portion across an edge of said die;  
        a first polymer layer over said horizontal level and on said first die, wherein said  
10     first polymer layer is the only one polymer layer between said first die and said  
patterned wiring layer, and wherein said patterned wiring layer ~~is being~~ connected to  
said first die through an opening in said first polymer layer and ~~is being~~ on said first  
polymer layer;  
        a passive device over said horizontal level; and  
15     a second polymer layer on said passive device.

232. (previously presented) The chip package in claim 231 further comprising a  
substrate joined with said first die, wherein said substrate is under said horizontal  
level.

20     233. (previously presented) The chip package in claim 232, wherein said substrate  
comprises polymer.

234. (previously presented) The chip package in claim 232, wherein said substrate  
25     comprises resin.

235. (previously presented) The chip package in claim 232, wherein said substrate  
comprises imide.

30     236. (previously presented) The chip package in claim 232, wherein said substrate  
comprises plastic.

237. (previously presented) The chip package in claim 232, wherein said substrate comprises thermosetting plastic.

Claims 238-243 (canceled)

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244. (previously presented) The chip package in claim 231, wherein said first polymer layer comprises polyimide (PI).

245. (previously presented) The chip package in claim 231, wherein said first polymer layer comprises benzocyclobutene (BCB).  
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246. (previously presented) The chip package in claim 231, wherein said first polymer layer comprises a porous structure.

15 Claims 247-255 (canceled)

256. (previously presented) The chip package in claim 231, wherein said second polymer layer comprises polyimide (PI).

20 257. (previously presented) The chip package in claim 231, wherein said second polymer layer comprises benzocyclobutene (BCB).

258. (previously presented) The chip package in claim 231, wherein said second polymer layer comprises a porous structure.

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259. (previously presented) The chip package in claim 231, wherein said top surface comprises multiple pads.

260. (currently amended) The chip package in claim 231, wherein said patterned wiring layer comprises a second portion connecting multiple internal circuits of said first die.  
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261. (currently amended) The chip package in claim 260, wherein said second portion is used to transmit a signal.
- 5 262. (currently amended) The chip package in claim 260, wherein said second portion is used to provide a power voltage.
263. (currently amended) The chip package in claim 260, wherein said second portion is used to provide a ground voltage.
- 10 264. (currently amended) The chip package in claim 231 further comprising a second die having a top surface at said horizontal level, wherein said patterned wiring layer comprises a second portion connecting said first die and said second die.
- 15 265. (previously presented) The chip package in claim 231 further comprising a film layer around said first die.
266. (previously presented) The chip package in claim 265, wherein said film layer comprises polymer.
- 20 267. (previously presented) The chip package in claim 265, wherein said film layer comprises epoxy.
268. (previously presented) The chip package in claim 265, wherein said film layer has a top surface at said horizontal level.
- 25 269. (previously presented) The chip package in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises solder.
- 30 270. (previously presented) The chip package in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises gold.
271. (previously presented) The chip package in claim 231, wherein said passive

device comprises a resistor.

272. (previously presented) The chip package in claim 231, wherein said passive device comprises a capacitor.

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273. (previously presented) The chip package in claim 231, wherein said passive device comprises an inductor.

274. (previously presented) The chip package in claim 231, wherein said passive device comprises a filter.

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275. (previously presented) The chip package in claim 231, wherein said passive device comprises a waveguide.

276. (previously presented) The chip package in claim 231, wherein said passive device comprises a micro electronic mechanical sensor (MEMS).

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277. (previously presented) The chip package in claim 231, wherein said passive device is not directly over said first die.

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Claim 278 (canceled)

279. (previously presented) The chip package in claim 231, wherein said passive device is connected to said first die.

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Claims 280-319 (canceled)

320. (currently amended) The chip package in claim 231, wherein said patterned wiring circuit-layer comprises copper.

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